Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) An input signal processing device comprising:

an input signal terminal that receives an input signal;

a connection inductance element that is connected to said input signal terminal at one end thereof;

a connection capacitance element that is connected to said input signal terminal at one end thereof;

a first grounding switching means that switches whether the other end of said connection inductance element is grounded or not; and

a second grounding switching means that switches whether the other end of said connection capacitance element is grounded or not.

2. (Original) The input signal processing device according to claim 1, further comprising:

a grounding capacitance element that is connected to the other end of said connection inductance element, and is grounded; and

a grounding inductance element that is connected to the other end of said connection capacitance element, and is grounded.

3. (Currently Amended) The input signal processing device according to claim 1 ~~or 2~~, wherein at least one of said first grounding switching means and said second grounding switching means is a semiconductor switch or an MEMS switch.

4. (Currently Amended) A high-frequency component acquisition method that uses the input signal processing device according to claim 1 ~~any one of claims 1 to 3~~ to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

5. (Currently Amended) A low-frequency component acquisition method that uses the input signal processing device according to claim 1 ~~any one of claims 1 to 3~~ to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

6. (New) The input signal processing device according to claim 2, wherein at least one of said first grounding switching means and said second grounding switching means is a semiconductor switch or an MEMS switch.

7. (New) A high-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

8. (New) A high-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

9. (New) A high-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

10. (New) A low-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

11. (New) A low-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

12. (New) A low-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.